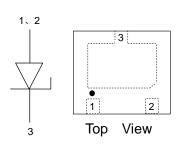


PTVSHC3N12VU

Transient Voltage Suppressor

Description

The PTVSHC3N12VU ESD protector is designed to replace multilayer varistors (MLVs) in portable applications such as cell phones, notebook computers, and PDA's. They feature large cross-sectional area junctions for conducting high transient currents, offer desirable electrical characteristics for board level protection, such as fast response time, lower operating voltage, lower clamping voltage and no device degradation when compared to MLVs. The PTVSHC3N12VU protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. The PTVSHC3N12VU is available in a DFN2×2-3L package with working voltages of 12 volt. It is used to meet the ESD immunity requirements of IEC 61000-4-2 (±30kV air, ±30kV contact discharge)



Feature

- > 5000W Peak pulse power per line (t_P = 8/20µs)
- DFN2x2-3L package
- Response time is typically < 1 ns</p>
- Protect one I/O or power line
- Low clamping Voltage
- RoHS compliant
- Transient protection for data lines to IEC 61000-4-2(ESD)
 ±30KV(air), ±30KV(contact); IEC 61000-4-4 (EFT) 80A (5/50ns)
 IEC 61000-4-5 (Lightning) 200A (8/20us)

Applications

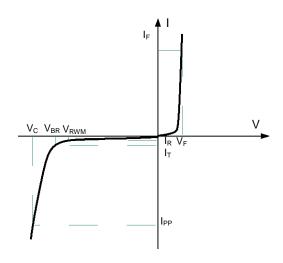
- Cell phone handsets and accessories
- Personal digital assistants (PDA's)
- Notebooks, desktops, and servers
- Portable instrumentation
- Cordless phones
- Digital cameras
 - Peripherals
 - MP3 players

Mechanical Characteristics

- Lead finish:100% matte Sn(Tin)
- Mounting position: Any
- ➤ Qualified max reflow temperature:260°C
- ➤ Pure tin plating: 7 ~ 17 um
- Pin flatness:≤3mil

Electronics Parameter

Symbol	Parameter	
V_{RWM}	Peak Reverse Working Voltage	
I _R	Reverse Leakage Current @ V _{RWM}	
V_{BR}	Breakdown Voltage @ I _T	
I _T	Test Current	
I _{PP}	Maximum Reverse Peak Pulse Current	
V _C	Clamping Voltage @ I _{PP}	
P _{PP}	Peak Pulse Power	
CJ	Junction Capacitance	
I _F	Forward Current	
V _F	Forward Voltage @ I _F	



Electrical characteristics per line@25℃ (unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Peak Reverse Working Voltage	V_{RWM}				12	٧
Breakdown Voltage	V_{BR}	I _t =1mA	14	14.5		V
Reverse Leakage Current	I _R	V _{RWM} =12V			1	μA
Maximum Reverse Peak Pulse	I _{PP}			200		Α
Clamping Voltage	V _C	I _{PP} =40A t _P = 8/20μs		16	18	V
Clamping Voltage	Vc	I _{PP} =90A t _P = 8/20µs		18	20	V
Clamping Voltage	Vc	$I_{PP}=140A$ $t_P = 8/20 \mu s$		20.5	24	V
Clamping Voltage	Vc	I _{PP} =200A t _P = 8/20μs		25	30	V
Junction Capacitance	C _j	V _R =0V f = 1MHz		1000	1500	pF

Notes: Measured from pin 3 to pin 1 and pin 2.

Absolute maximum rating@25℃

Rating	Symbol	Value	Units
Peak Pulse Power (t _P = 8/20µS)	P _{pp}	5000	W
Lead Soldering Temperature	TL	260 (10 sec)	$^{\circ}$
Operating Temperature	TJ	-55 to +150	$^{\circ}$
Storage Temperature	T _{STG}	-55 to +150	$^{\circ}$

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Typical Characteristics

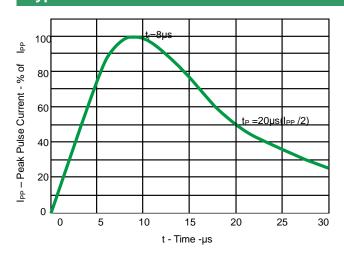


Fig 1.Pulse Waveform

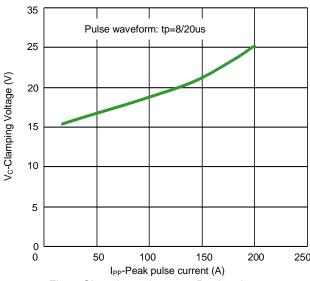
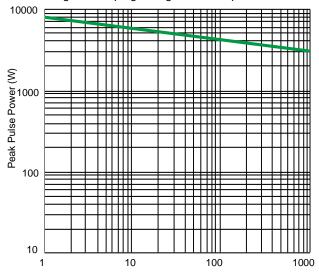


Fig 3. Clamping voltage vs. Peak pulse current



Pulse Duration(us)
Fig 5. Non Repetitive Peak Pulse Power vs. Pulse time

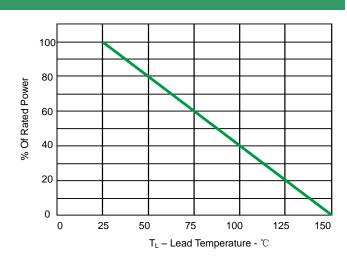


Fig 2.Power Derating Curve

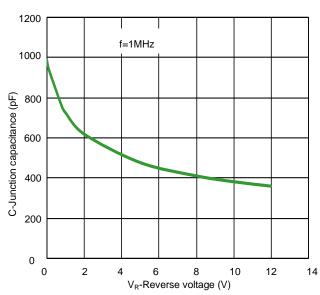
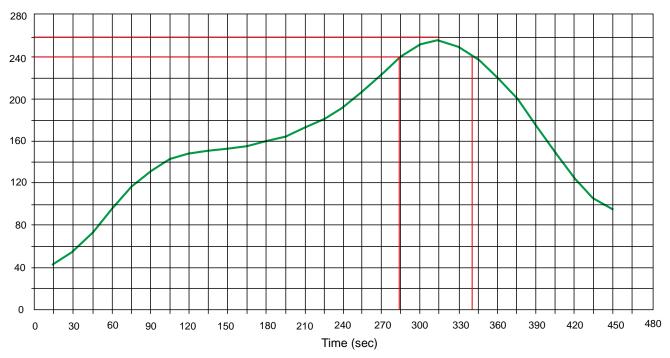


Fig 4. Capacitance vs. Reveres voltage

Solder Reflow Recommendation

Peak Temp=257°C, Ramp Rate=0.802deg. °C/sec

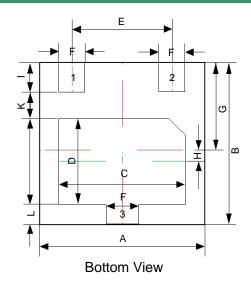


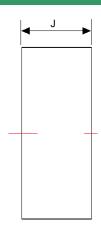
PCB Design

For TVS diodes a low-ohmic and low-inductive path to chassis earth is absolutely mandatory in order to achieve good ESD protection. Novices in the area of ESD protection should take following suggestions to heart:

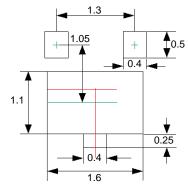
- > Do not use stubs, but place the cathode of the TVS diode directly on the signal trace.
- Do not make false economies and save copper for the ground connection.
- Place via holes to ground as close as possible to the anode of the TVS diode.
- > Use as many via holes as possible for the ground connection.
- Keep the length of via holes in mind! The longer the more inductance they will have.

Product dimension (DFN2×2-3L)





Dim	Millimeters		
Dilli	MIN	MAX	
Α	1.90	2.10	
В	1.90	2.10	
С	1.40	1.60	
D	0.90	1.10	
E	1.30BSC		
F	0.25	0.35	
G	0.95	1.05	
Н	0.20	0.30	
1	0.35	0.45	
J		0.65	
K	0.30	0.35	
	0.15	0.20	



Recommended Soldering Pad

Unit:mm

Ordering information

Dev	vice	Package	Shipping
PTVSHC	3N12VU	DFN2×2-3L (Pb-Free)	3000 / Tape & Reel

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